



## BONDLINE BL2000

Laser Bar Soldering System

The BL2000 is ficonTEC's automated high performance laser diode bar soldering system and offers a higher throughput than the BL1000. In addition to the features of the BL1000, the BL2000 offers 6-axis alignment of the laser bar with an accuracy of +/-1µm and the ability to be equipped with a fully automated visual device inspection. Inspection of the P-side, N-side and the facets is available.



### FEATURES

- + Fully automated bar and single chip (die) bonding
- + Pick up from BlueTape, GelPack and customized trays
- + Alignment & post bond accuracy down to +/-1 µm
- + Alignment with up to 6 axis
- + Solder temperature up to 400°C
- + High heating and cooling rate
- + Inert gas supply
- + Integrated formic acid gas generator
- + Adjustable bonding force
- + Excellent bond line thickness reproducibility
- + Minimum Laser diode bar "smile"
- + Flip Chip option
- + Automated optical facet, P-and N-side inspection option
- + Laser test station option
- + Full serial number and device tracking
- + Open Software architecture
- + Flexible integration of external test equipment
- + SQL-Database connectivity

### APPLICATIONS

- + Laser Diode bar to heat sink soldering
- + High precision die bonding of opto electronic devices
- + Assembly of DPSS-Laser
- + MEMS

Please contact us for further information.